

In The Claims

Claims 1-230 (canceled)

- 5 231. (currently amended) A chip package circuit component comprising:
a first die having a top surface at a horizontal level;
a patterned wiring layer over said horizontal level, wherein said patterned wiring
layer comprises a portion across a side an edge of said die;
a first polymer layer over said horizontal level and on said first die, wherein said
10 first polymer layer is the only one polymer layer between said first die and said
patterned wiring layer, said patterned wiring layer being connected to said first die
through an opening in said first polymer layer and being on said first polymer layer;
a passive device over said horizontal level; and
a second polymer layer on over said passive device.
- 15 232. (currently amended) The chip package circuit component in claim 231 further
comprising a substrate joined with said first die, wherein said substrate is under said
horizontal level.
- 20 233. (currently amended) The chip package circuit component in claim 232, wherein
said substrate comprises polymer.
234. (currently amended) The chip package circuit component in claim 232, wherein
said substrate comprises resin.
- 25 235. (currently amended) The chip package circuit component in claim 232, wherein
said substrate comprises imide.
236. (currently amended) The chip package circuit component in claim 232, wherein
30 said substrate comprises plastic.
237. (currently amended) The chip package circuit component in claim 232, wherein

said substrate comprises thermosetting plastic.

Claims 238-243 (canceled)

5 244. (currently amended) The chip package circuit component in claim 231, wherein said first polymer layer comprises polyimide (PI).

245. (currently amended) The chip package circuit component in claim 231, wherein said first polymer layer comprises benzocyclobutene (BCB).

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246. (currently amended) The chip package circuit component in claim 231, wherein said first polymer layer comprises a porous structure.

Claims 247-255 (canceled)

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256. (currently amended) The chip package circuit component in claim 231, wherein said second polymer layer comprises polyimide (PI).

257. (currently amended) The chip package circuit component in claim 231, wherein said second polymer layer comprises benzocyclobutene (BCB).

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258. (currently amended) The chip package circuit component in claim 231, wherein said second polymer layer comprises a porous structure.

259. (currently amended) The chip package circuit component in claim 231, wherein said top surface comprises multiple pads.

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260. (currently amended) The chip package circuit component in claim 231, wherein said patterned wiring layer comprises a portion connecting multiple internal circuits of said first die.

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261. (currently amended) The chip package circuit component in claim 260, wherein

said portion is used to transmit a signal.

262. (currently amended) The chip package circuit component in claim 260, wherein said portion is used to provide a power voltage.

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263. (currently amended) The chip package circuit component in claim 260, wherein said portion is used to provide a ground voltage.

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264. (currently amended) The chip package circuit component in claim 231 further comprising a second die having a top surface at said horizontal level, wherein said patterned wiring layer comprises a portion connecting said first die and said second die.

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265. (currently amended) The chip package circuit component in claim 231 further comprising a film layer around said first die.

266. (currently amended) The chip package circuit component in claim 265, wherein said film layer comprises polymer.

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267. (currently amended) The chip package circuit component in claim 265, wherein said film layer comprises epoxy.

268. (currently amended) The chip package circuit component in claim 265, wherein said film layer has a top surface at said horizontal level.

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269. (currently amended) The chip package circuit component in claim 231 further comprising a bump over said horizontal level, wherein said bump comprises solder.

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270. (currently amended) The chip package circuit component in claim 231 further comprising a bump over said horizontal level, wherein said bump comprises gold.

271. (currently amended) The chip package circuit component in claim 231, wherein

said passive device comprises a resistor.

272. (currently amended) The chip package circuit component in claim 231, wherein said passive device comprises a capacitor.

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273. (currently amended) The chip package circuit component in claim 231, wherein said passive device comprises an inductor.

274. (currently amended) The chip package circuit component in claim 231, wherein
10 said passive device comprises a filter.

275. (currently amended) The chip package circuit component in claim 231, wherein said passive device comprises a waveguide.

15 276. (currently amended) The chip package circuit component in claim 231, wherein said passive device comprises a micro electronic mechanical sensor (MEMS).

277. (currently amended) The chip package circuit component in claim 231, wherein
20 said passive device is not directly over said first die.

Claim 278 (canceled)

279. (currently amended) The chip package circuit component in claim 231, wherein
25 said passive device is connected to said first die.

Claims 280-319 (canceled)

320. (currently amended) The chip package circuit component in claim 231, wherein
30 said patterned circuit layer comprises copper.